



Product/Process Change Notice - PCN 18_0071 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Bump Site Transfer for 6" Wafer Bumping

Publication Date: 03-May-2018

Effectivity Date: 05-Aug-2018 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change:

Bumping Site change from ASE Kaohsiung Taiwan(AEG) to Chipbond, Taiwan(CB4)
UBM Seed layer change from Al(0.4)/NiV(0.3)/Cu(0.8) to Ti(0.2)/Cu(0.4)/Cu(8.6).

See attached Summary of Change in the supporting documents section of this PCN for details.

Reason For Change:

ASE Kaohsiung 6" wafer bumping capability is being discontinued and will no longer be capable of manufacturing the wafer bumping process for 6" wafer. Moving the bumping of select products to ChipBond, where several of ADI's parts are bumped.

ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, materials, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from different manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability:

No impact to form, fit, function and reliability.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Detailed Change Description

ADI_PCN_18_0071_Rev_-_Summary of Change AEG to CB4.pdf

Attachment 2: Type: Qualification Results Summary

ADI_PCN_18_0071_Rev_-_Qualification Results Summary for Direct Bump WLCSP at Chipbond.pdf

Attachment 3: Type: Qualification Results Summary

ADI_PCN_18_0071_Rev_-_Qualification Results Summary for Cu RDL Bump WLCSP at Chipbond.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (6)

AD8311 / AD8311ACBZ-P2	AD8311 / AD8311ACBZ-P7	AD8312 / AD8312ACBZ-P2	AD8312 / AD8312ACBZ-P7	ADL5500 / ADL5500ACBZ-P7
OP482 / OP482ACBZ-R7				

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	03-May-2018	05-Aug-2018	Initial Release

Analog Devices, Inc.

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